PCN # 1640

DATE: January 3, 2018

EXPECTED PCN SHIP DATE: January 3, 2018



Quality Assurance 160 Rio Robles San Jose, CA 95134

www.maximintegrated.com

	PROCESS CHANGE NOTICE
X	PRODUCT CHANGE NOTICE

21	GIRODUCI		MOTICE			
THAT MA			IG CATEGORIE	SS:		
WAFER FAB	X ASSEMBL	Y	TEST	ELEC/MECH SP	PECS	
	AFFECTED	PRODUCT	Γ:			
Orderin	g P/N: (See PN lis	ting XLS in	PCN ZIP file)			
		1				
mic chip carrier, 20 & 28	S leads)					
lucts in LCC nackages a	are being discontin	l ued at ATP	due to continuo	us decreasing demand	Need to move	
1 0	are being discontin		due to continuo	us decreasing demand.		
the form, fit or function	of these devices.					
im Integrated maintains	full traceability by	device ma	rking, packaging	labels and shipment doc	uments.	
nge Notification System	is designed to kee	ep our custo	omer base apprise	ed of major product, man	nufacturing, or	
Nasser Ali Chaovche						
			Nasser A	AliChaouche / PCN Coord	dinator	
please contact either of	the people listed b	elow.				
xim Integrated Compa	ny Representativ	e or	Nasser AliCh	aouche, PCN Coordinato	r	
				<i>'</i>		
	MAXIM INTEGRA THAT MA THAT MA WAFER FAB Orderin Tent sole sourced assemble illippines). Impacted devenic chip carrier, 20 & 28 ducts in LCC packages ally. The form, fit or function the form, fit or function the form of th	MAXIM INTEGRATED HEREBY IS THAT MAY AFFECT THE FOLLOW WAFER FAB AFFECTED Ordering P/N: (See PN listent sole sourced assembly facility: ATP illippines). Impacted devices are in LCC mic chip carrier, 20 & 28 leads) ducts in LCC packages are being discontingly. The form, fit or function of these devices. The form is the form is designed to keep the form is designed to keep the people listed by the people	MAXIM INTEGRATED HEREBY ISSUES NOT THAT MAY AFFECT THE FOLLOWIN AFFECTED PRODUCT Ordering P/N: (See PN listing XLS in rent sole sourced assembly facility: ATP illippines). Impacted devices are in LCC mic chip carrier, 20 & 28 leads) ducts in LCC packages are being discontinued at ATP by. The the form, fit or function of these devices. The form is designed to keep our custom in the people listed below.	THAT MAY AFFECT THE FOLLOWING CATEGORIE WAFER FAB AFFECTED PRODUCT: Ordering P/N: (See PN listing XLS in PCN ZIP file) Tent sole sourced assembly facility: ATP illippines). Impacted devices are in LCC mic chip carrier, 20 & 28 leads) ducts in LCC packages are being discontinued at ATP due to continuolly. The form, fit or function of these devices. The form, fit or function of these devices. The form of the form of the form of these devices. The form of function of these devices are in LCC marking, packaging on the form of the form	MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE THAT MAY AFFECT THE FOLLOWING CATEGORIES: WAFER FAB AFFECTED PRODUCT: Ordering P/N: (See PN listing XLS in PCN ZIP file) Tent sole sourced assembly facility: ATP illippines). Impacted devices are in LCC mic chip carrier, 20 & 28 leads) ducts in LCC packages are being discontinued at ATP due to continuous decreasing demand. In the form, fit or function of these devices. The form, fit or function of these devices. The form is the form of the form of these devices. The form is the form of the form of these devices. The form is the form of the form of these devices. The form is the form of the form of these devices. The form is the form of the form of the form of these devices. The form is the form of t	

Document Title: Product Change Notice - Notification Only

Document ID: 18-0182